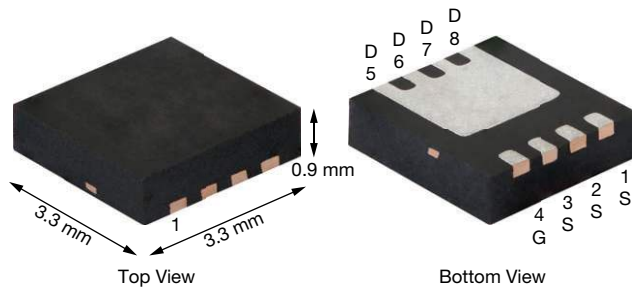


N-Channel 20 V (D-S) Fast Switching MOSFET

PowerPAK® 1212-8SH


| PRODUCT SUMMARY | |
|--|--------|
| V_{DS} (V) | 20 |
| $R_{DS(on)}$ max. (Ω) at $V_{GS} = 10$ V | 0.0049 |
| $R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5$ V | 0.0061 |
| Q_g typ. (nC) | 20 |
| I_D (A) | 22 |
| Configuration | Single |

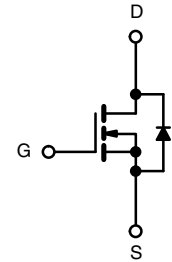
FEATURES

- TrenchFET® Gen II power MOSFET for ultra low on-resistance
- 100 % R_g tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
 COMPLIANT
 HALOGEN
FREE

APPLICATIONS

- Synchronous rectification
- Point-of-load converters
- Protection devices
- Hot swap



N-Channel MOSFET

ORDERING INFORMATION

| | |
|---------------------------------|------------------|
| Package | PowerPAK 1212-8 |
| Lead (Pb)-free and halogen-free | SiSH108DN-T1-GE3 |

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)

| PARAMETER | SYMBOL | 10 s | STEADY STATE | UNIT |
|--|----------------|---------------|--------------|------|
| Drain-source voltage | V_{DS} | 20 | 20 | V |
| Gate-source voltage | V_{GS} | ± 16 | ± 16 | |
| Continuous drain current ($T_J = 150$ °C) ^a | I_D | $T_A = 25$ °C | 22 | A |
| | | $T_A = 70$ °C | 17.6 | |
| Pulsed drain current | I_{DM} | 60 | 60 | A |
| Continuous source current (diode conduction) ^a | I_S | 3.2 | 1.3 | |
| Single avalanche current | I_{AS} | L = 0.1 mH | 22 | mJ |
| Single avalanche energy | | | E_{AS} | |
| Maximum power dissipation ^a | P_D | $T_A = 25$ °C | 3.8 | W |
| | | $T_A = 70$ °C | 2.0 | |
| Operating junction and storage temperature range | T_J, T_{stg} | -55 to +150 | | °C |
| Soldering recommendations (peak temperature) ^{b, c} | | 260 | | |

THERMAL RESISTANCE RATINGS

| PARAMETER | SYMBOL | TYPICAL | MAXIMUM | UNIT |
|--|------------|---------------|---------|------|
| Maximum junction-to-ambient ^a | R_{thJA} | $t \leq 10$ s | 24 | °C/W |
| | | Steady state | 65 | |
| Maximum junction-to-case (drain) | R_{thJC} | 1.9 | 2.4 | |

Notes

- Surface mounted on 1" x 1" FR4 board
- See solder profile (www.vishay.com/doc?73257). The PowerPAK 1212-8SH is a leadless package within the PowerPAK 1212-8 package family. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components



| SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted) | | | | | | |
|---|--------------|---|------|--------|-----------|---------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT |
| Static | | | | | | |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$ | 1 | - | 2 | V |
| Gate body leakage | I_{GSS} | $V_{DS} = 0\text{ V}$, $V_{GS} = \pm 16\text{ V}$ | - | - | ± 100 | nA |
| Zero gate voltage drain current | I_{DSS} | $V_{DS} = 20\text{ V}$, $V_{GS} = 0\text{ V}$ | - | - | 1 | μA |
| | | $V_{DS} = 20\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 55\text{ }^\circ\text{C}$ | - | - | 5 | |
| On-state drain current ^a | $I_{D(on)}$ | $V_{DS} \geq 5\text{ V}$, $V_{GS} = 10\text{ V}$ | 40 | - | - | A |
| Drain-source on-state resistance ^a | $R_{DS(on)}$ | $V_{GS} = 10\text{ V}$, $I_D = 22\text{ A}$ | - | 0.0041 | 0.0049 | Ω |
| | | $V_{GS} = 4.5\text{ V}$, $I_D = 19.7\text{ A}$ | - | 0.0050 | 0.0061 | |
| Forward transconductance ^a | g_{fs} | $V_{DS} = 15\text{ V}$, $I_D = 22\text{ A}$ | - | 88 | - | S |
| Diode forward voltage ^a | V_{SD} | $I_S = 3.2\text{ A}$, $V_{GS} = 0\text{ V}$ | - | 0.75 | 1.2 | V |
| Dynamic ^b | | | | | | |
| Total gate charge | Q_g | $V_{DS} = 10\text{ V}$, $V_{GS} = 4.5\text{ V}$, $I_D = 22\text{ A}$ | - | 20 | 30 | nC |
| Gate-source charge | Q_{gs} | | - | 6.3 | - | |
| Gate-drain charge | Q_{gd} | | - | 4.9 | - | |
| Gate resistance | R_g | $f = 1\text{ MHz}$ | 0.7 | 1.4 | 2.1 | Ω |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD} = 20\text{ V}$, $R_L = 20\text{ }\Omega$ $I_D \cong 1\text{ A}$, $V_{GEN} = 10\text{ V}$, $R_g = 6\text{ }\Omega$ | - | 10 | 15 | ns |
| Rise time | t_r | | - | 10 | 15 | |
| Turn-off delay time | $t_{d(off)}$ | | - | 60 | 130 | |
| Fall time | t_f | | - | 10 | 15 | |
| Source-drain reverse recovery time | t_{rr} | $I_F = 3.2\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$ | - | 30 | 60 | nC |
| Reverse recovery charge | Q_{rr} | | - | 20 | 36 | |

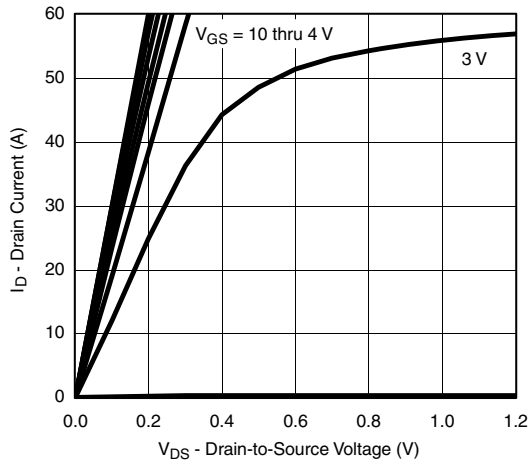
Notes

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing

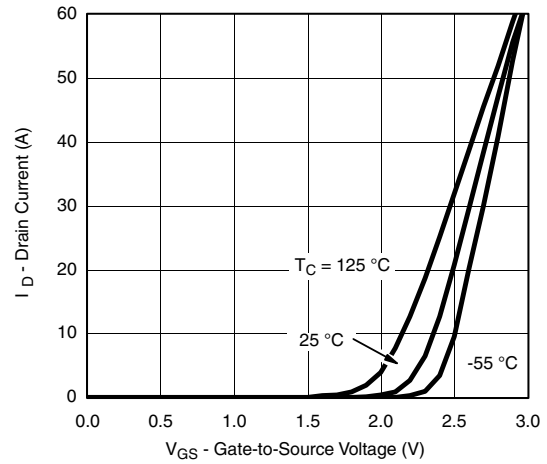
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



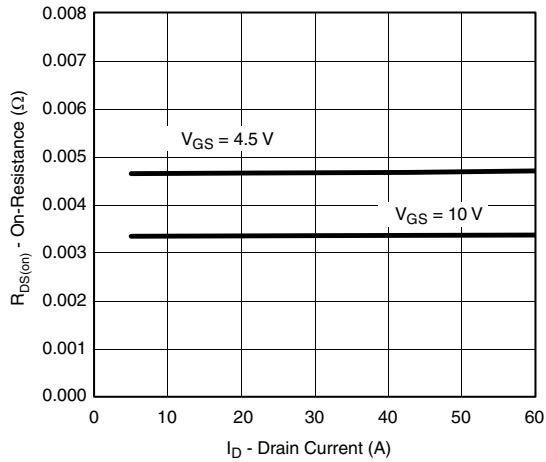
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



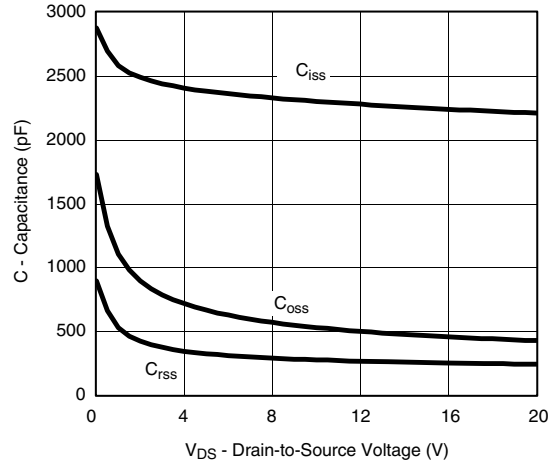
Output Characteristics



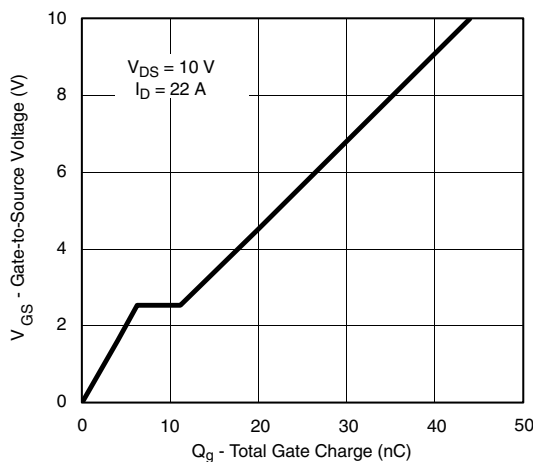
Transfer Characteristics



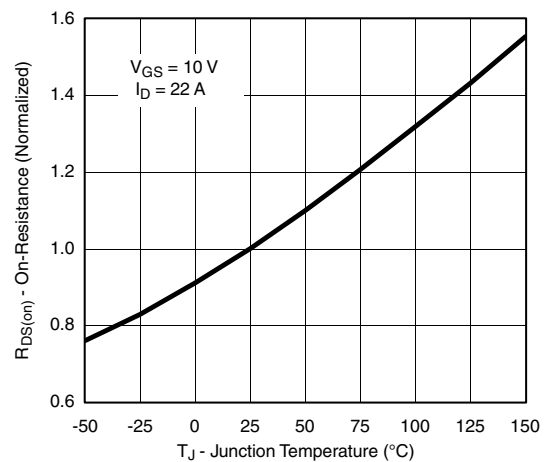
On-Resistance vs. Drain Current



Capacitance



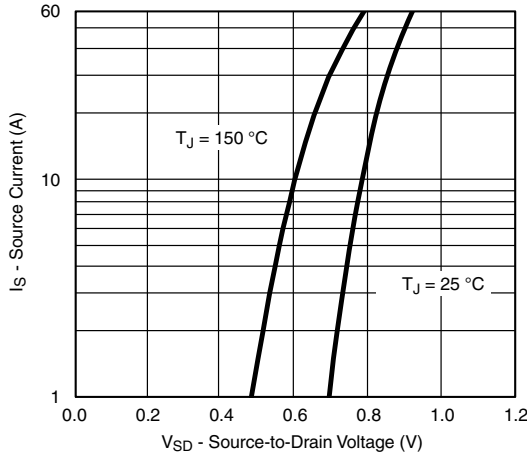
Gate Charge



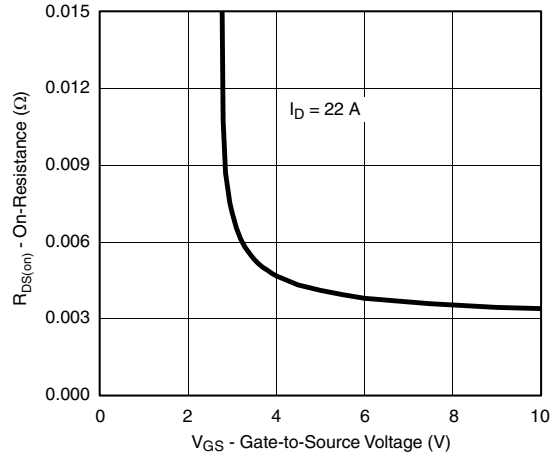
On-Resistance vs. Junction Temperature



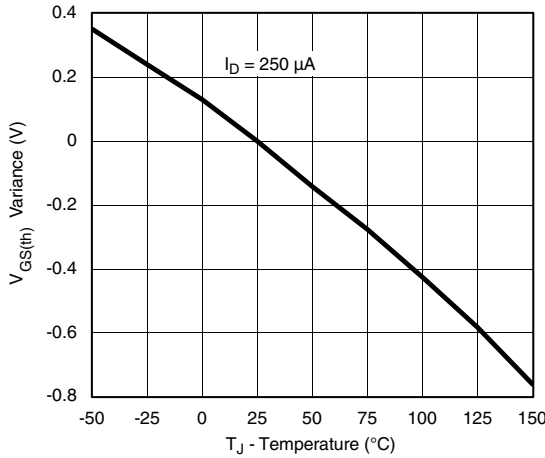
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



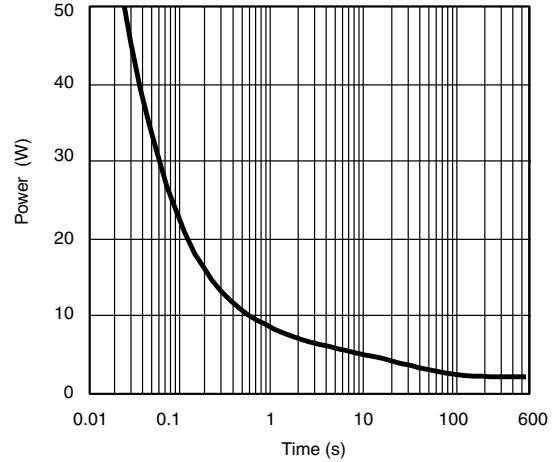
Source-Drain Diode Forward Voltage



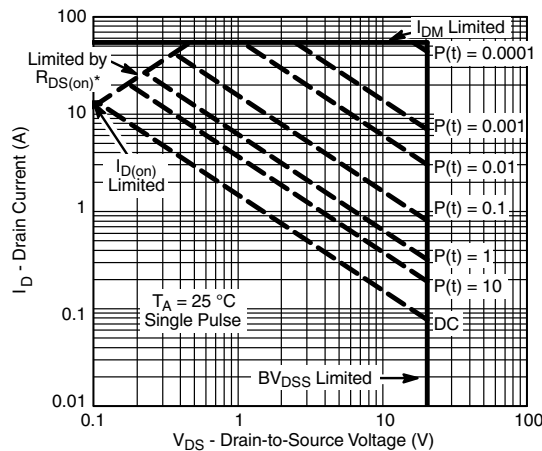
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

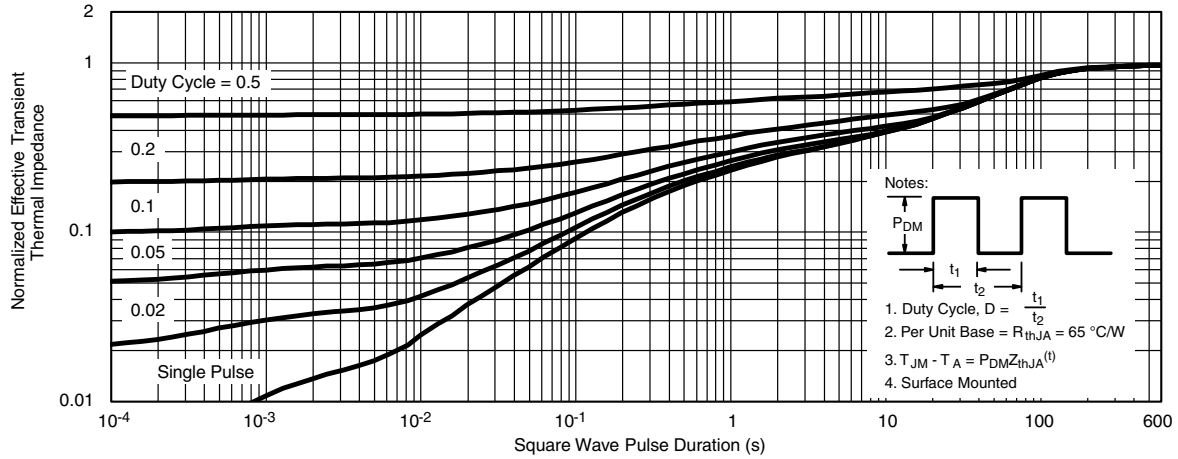


* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

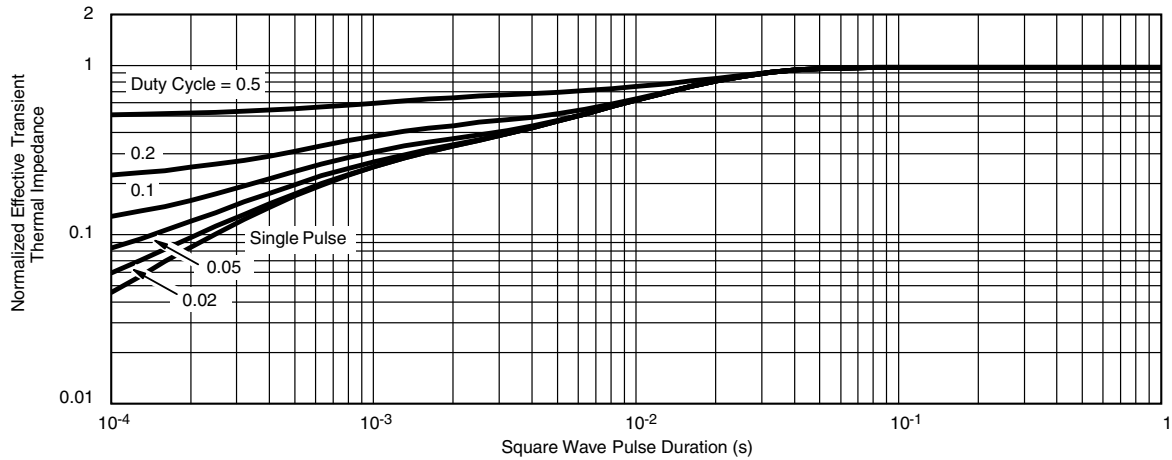
Safe Operating Area



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



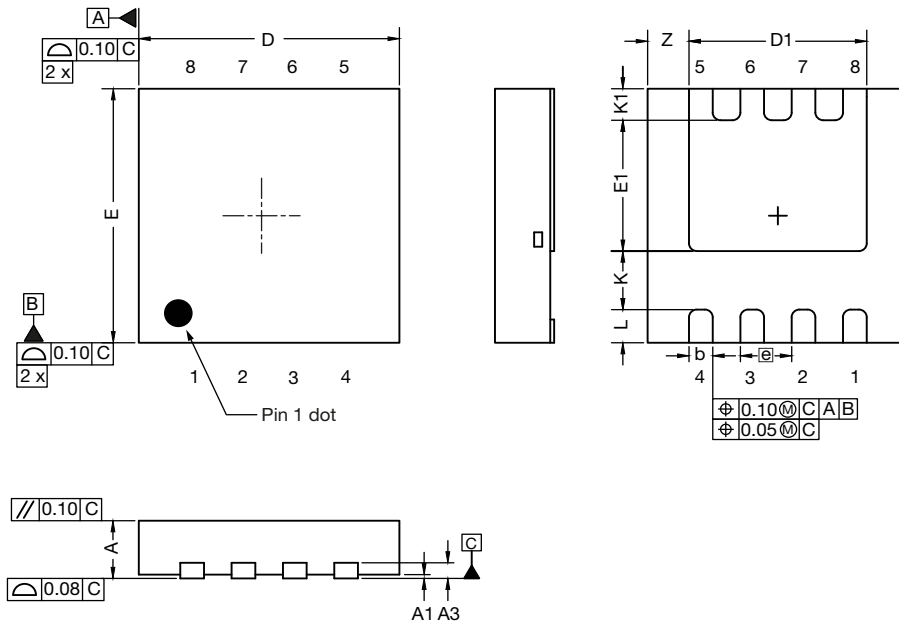
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?79330.

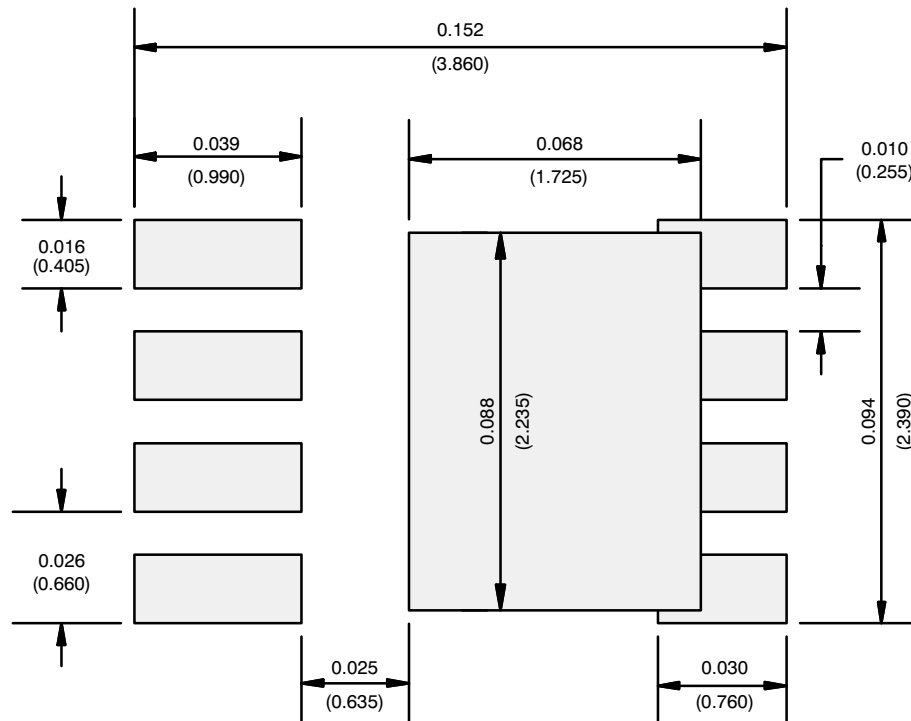
Case Outline for PowerPAK[®] 1212-SWLH and PowerPAK[®] 1212-8SH



| DIM. | MILLIMETERS | | | INCHES | | |
|------|-------------|------|------|------------|-------|-------|
| | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. |
| A | 0.82 | 0.90 | 0.98 | 0.032 | 0.035 | 0.038 |
| A1 | 0.00 | - | 0.05 | 0.000 | - | 0.002 |
| A3 | 0.20 ref. | | | 0.008 ref. | | |
| b | 0.25 | 0.30 | 0.35 | 0.010 | 0.012 | 0.014 |
| D | 3.20 | 3.30 | 3.40 | 0.126 | 0.130 | 0.134 |
| D1 | 2.15 | 2.25 | 2.35 | 0.085 | 0.089 | 0.093 |
| E | 3.20 | 3.30 | 3.40 | 0.126 | 0.130 | 0.134 |
| E1 | 1.60 | 1.70 | 1.80 | 0.063 | 0.067 | 0.071 |
| e | 0.65 bsc. | | | 0.026 bsc. | | |
| K | 0.76 ref. | | | 0.030 ref. | | |
| K1 | 0.41 ref. | | | 0.016 ref. | | |
| L | 0.33 | 0.43 | 0.53 | 0.013 | 0.017 | 0.021 |
| Z | 0.525 ref. | | | 0.021 ref. | | |

ECN: S20-0930-Rev. C, 07-Dec-2020
DWG: 6062

RECOMMENDED MINIMUM PADS FOR PowerPAK® 1212-8 Single



Recommended Minimum Pads
Dimensions in Inches/(mm)

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